

Amendments to the Specification

Please replace the paragraphs beginning at page 1, line 1, with the following rewritten paragraphs:

STACKED BALL GRID ARRAY PACKAGE

BACKGROUND OF THE INVENTION

This invention relates in general to the packaging of integrated circuits and more specifically to ball grid array (BGA) packages. In particular, this invention relates to the use of an interposer in a and may be referred to as a ball grid array package or a stacked ball grid array.